

**IN THE CLAIMS**

This listing replaces all prior listings of claims:

1. (Cancelled).
2. (Currently Amended) A semiconductor manufacturing apparatus comprising:  
an electrolytic plating chamber with which an electrolytic plating apparatus responsible for electrolytic plating of a substrate is constructed;  
an electrolytic polishing chamber with which an electrolytic polishing apparatus responsible for electrolytic polishing of the substrate is constructed; and  
a conveying chamber having installed therein a conveying instrument responsible for loading/unloading of the substrate to or from said electrolytic plating chamber and to or from said electrolytic polishing chamber, and being connected respectively to said electrolytic plating chamber and said electrolytic polishing chamber,  
wherein,  
said electrolytic plating chamber with which the electrolytic plating apparatus is constructed comprises:  
a holder for holding the substrate;  
a cup provided so as to oppose to said holder and is capable of forming a closed space, into which an electrolytic plating solution can be filled, together with the substrate held by said holder; ~~and~~  
a nozzle provided outside of said cup and affixed on a peripheral sidewall of said chamber for supplying the process liquid onto a surface of the substrate held by said holder; and  
an inlet portion and an outlet portion, both provided through peripheral walls of said chamber, for supplying gas into and removing gas out of said chamber, respectively, and said inlet portion being distinct from said nozzle.

3. (Original) The semiconductor manufacturing apparatus as claimed in Claim 2, wherein said process liquid comprises a cleaning liquid.

4. (Currently Amended) A semiconductor manufacturing apparatus comprising:  
an electrolytic plating chamber with which an electrolytic plating apparatus responsible for electrolytic plating of a substrate is constructed;

an electrolytic polishing chamber with which an electrolytic polishing apparatus responsible for electrolytic polishing of the substrate is constructed; and

a conveying chamber having installed therein a conveying instrument responsible for loading/unloading of the substrate to or from said electrolytic plating chamber and to or from said electrolytic polishing chamber, and being connected respectively to said electrolytic plating chamber and said electrolytic polishing chamber,

wherein,

said electrolytic polishing chamber with which the electrolytic polishing apparatus is constructed comprises:

a holder for holding the substrate;

a cup provided so as to oppose to said holder and is capable of forming a closed space, into which an electrolytic polishing solution can be filled, together with the substrate held by said holder; and

a nozzle provided outside of said cup and affixed on a peripheral sidewall of said chamber for supplying the process liquid onto a surface of the substrate held by said holder; and an inlet portion and an outlet portion, both provided through peripheral walls of said chamber, for supplying gas into and removing gas out of said chamber, respectively, and said inlet portion being distinct from said nozzle.

5. (Previously Presented) The semiconductor manufacturing apparatus as claimed in Claim 4, wherein said nozzle for supplying the process liquid comprises:

a nozzle provided outside of said cup for supplying a cleaning liquid onto the surface of the substrate; and

a nozzle provided outside of said cup for supplying an etching solution onto the surface of the substrate.

6. (Currently Amended) A semiconductor manufacturing apparatus comprising:  
an electrolytic plating chamber with which an electrolytic plating apparatus responsible for electrolytic plating of a substrate is constructed;  
an electrolytic polishing chamber with which an electrolytic polishing apparatus responsible for electrolytic polishing of the substrate is constructed;  
an electroless plating chamber with which an electroless plating apparatus responsible for electroless plating of the substrate is constructed;  
an annealing chamber with which an annealing apparatus responsible for annealing of the substrate is constructed; and  
a conveying chamber having installed therein a conveying instrument responsible for loading/unloading of the substrate to or from said electrolytic plating chamber, to or from said electrolytic polishing chamber, to or from said electroless plating chamber, and to or from said annealing chamber, and being connected respectively to said electrolytic plating chamber, said electrolytic polishing chamber, said electroless plating chamber and said annealing chamber, and said conveying chamber being connected with a liquid treatment chamber for supplying a process liquid,  
wherein,  
said liquid treatment chamber comprises:  
a holder for holding the substrate,  
a cup provided so as to oppose to said holder and is capable of forming a closed space, into which an electrolytic plating solution can be filled, together with the substrate held by said holder, ~~and~~  
a nozzle provided outside of said cup and affixed on a peripheral sidewall of said chamber for supplying the process liquid onto a surface of the substrate held by said holder; and

an inlet portion and an outlet portion, both provided through peripheral walls of said chamber, for supplying gas into and removing gas out of said chamber, respectively, and said inlet portion being distinct from said nozzle.

7. (Previously Presented) The semiconductor manufacturing apparatus as claimed in Claim 6, wherein:

said conveying instrument is responsible for loading/unloading of the substrate to or from said electrolytic plating chamber, to or from said electrolytic polishing chamber, to or from said electroless plating chamber, and to or from said annealing chamber, and is also responsible for loading/unloading of the substrate to or from said liquid treatment chamber.

8. (Cancelled).

9. (Previously Presented) The semiconductor manufacturing apparatus as claimed in Claim 6, wherein said nozzle for supplying the process liquid comprises:

a nozzle provided outside of said cup for supplying a cleaning liquid onto the surface of the substrate; and

a nozzle provided outside of said cup for supplying an etching solution onto the surface of the substrate.

10. (Previously Presented) The semiconductor manufacturing apparatus as claimed in Claim 6, wherein said electrolytic plating chamber with which the electrolytic plating apparatus is constructed comprises:

a holder for holding the substrate;

a cup provided so as to oppose to said holder and is capable of forming a closed space, into which an electrolytic plating solution can be filled, together with the substrate held by said holder; and

a nozzle provided outside of said cup for supplying a process liquid onto a surface of the substrate held by said holder.

11. (Original) The semiconductor manufacturing apparatus as claimed in Claim 10, wherein said process liquid comprises a cleaning liquid.

12. (Previously Presented) The semiconductor manufacturing apparatus as claimed in Claim 6, wherein said electrolytic polishing chamber with which the electrolytic polishing apparatus is constructed comprises:

a holder for holding the substrate;

a cup provided so as to oppose to said holder and is capable of forming a closed space, into which an electrolytic polishing solution can be filled, together with the substrate held by said holder; and

a nozzle provided outside of said cup for supplying a process liquid onto a surface of the substrate held by said holder.

13. (Previously Presented) The semiconductor manufacturing apparatus as claimed in Claim 12, wherein said nozzle for supplying the process liquid comprises:

a nozzle provided outside of said cup for supplying a cleaning liquid onto a surface of the substrate; and

a nozzle provided outside of said cup for supplying an etching solution onto a surface of the substrate.

14. – 18. (Cancelled)